

DS90LV049 3V LVDS Dual Line Driver with Dual Line Receiver

Check for Samples: [DS90LV049](#)

FEATURES

- Up to 400 Mbps Switching Rates
- Flow-Through Pinout Simplifies PCB Layout
- 50 ps Typical Driver Channel-to-Channel Skew
- 50 ps Typical Receiver Channel-to-Channel Skew
- 3.3 V Single Power Supply Design
- TRI-STATE Output Control
- Internal Fail-Safe Biasing of Receiver Inputs
- Low Power Dissipation (70 mW at 3.3 V Static)
- High Impedance on LVDS Outputs on Power Down
- Conforms to TIA/EIA-644-A LVDS Standard
- Industrial Operating Temperature Range (–40°C to +85°C)
- Available in Low Profile 16 Pin TSSOP Package

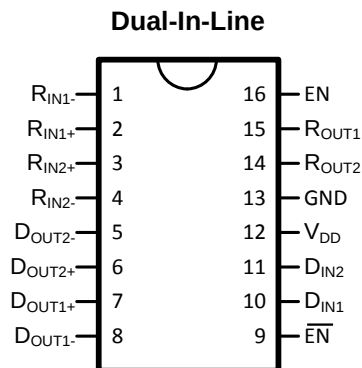
DESCRIPTION

The DS90LV049 is a dual CMOS flow-through differential line driver-receiver pair designed for applications requiring ultra low power dissipation, exceptional noise immunity, and high data throughput. The device is designed to support data rates in excess of 400 Mbps utilizing Low Voltage Differential Signaling (LVDS) technology.

The DS90LV049 drivers accept LVTTTL/LVCMOS signals and translate them to LVDS signals. On the other hand, the receivers accept LVDS signals and translate them to 3 V CMOS signals. The LVDS input buffers have internal failsafe biasing that places the outputs to a known H (high) state for floating receiver inputs. In addition, the DS90LV049 supports a TRI-STATE function for a low idle power state when the device is not in use.

The EN and $\overline{\text{EN}}$ inputs are ANDed together and control the TRI-STATE outputs. The enables are common to all four gates.

Connection Diagram



Order Number DS90LV049TMT
Order Number DS90LV049TMTX (Tape and Reel)
PW0016A Package



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Functional Diagram

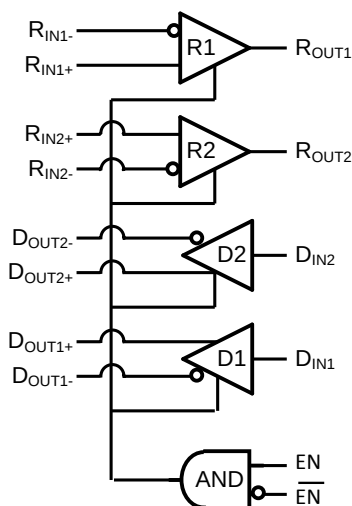


Table 1. TRUTH TABLE

EN	$\overline{\text{EN}}$	LVDS Out	LVC MOS Out
L or Open	L or Open	OFF	OFF
H	L or Open	ON	ON
L or Open	H	OFF	OFF
H	H	OFF	OFF



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

Supply Voltage (V_{DD})	–0.3 V to +4 V
LVCMOS Input Voltage (D_{IN})	–0.3 V to ($V_{DD} + 0.3$ V)
LVDS Input Voltage (R_{IN+} , R_{IN-})	–0.3 V to +3.9 V
Enable Input Voltage (EN , $\overline{EN}$)	–0.3 V to ($V_{DD} + 0.3$ V)
LVCMOS Output Voltage (R_{OUT})	–0.3 V to ($V_{DD} + 0.3$ V)
LVDS Output Voltage (D_{OUT+} , D_{OUT-})	–0.3 V to +3.9 V
LVCMOS Output Short Circuit Current (R_{OUT})	100 mA
LVDS Output Short Circuit Current (D_{OUT+} , D_{OUT-})	24 mA
LVDS Output Short Circuit Current Duration (D_{OUT+} , D_{OUT-})	Continuous
Storage Temperature Range	–65°C to +150°C
Lead Temperature Range	
Soldering (4 sec.)	+260°C
Maximum Junction Temperature	+150°C
Maximum Package Power Dissipation @ +25°C	
PW0016A Package	866 mW
Derate PW0016A Package	6.9 mW/°C above +25°C
ESD Rating	
(HBM, 1.5 k Ω , 100 pF)	≥ 7 kV
(MM, 0 Ω , 200 pF)	≥ 250 V

- (1) “Absolute Maximum Ratings” are those values beyond which the safety of the device cannot be specified. They are not meant to imply that the devices should be operated at these limits. [ELECTRICAL CHARACTERISTICS](#) specifies conditions of device operation.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

RECOMMENDED OPERATING CONDITIONS

	Min	Typ	Max	Units
Supply Voltage (V_{DD})	+3.0	+3.3	+3.6	V
Operating Free Air Temperature (T_A)	–40	+25	+85	°C

ELECTRICAL CHARACTERISTICS

Over supply voltage and operating temperature ranges, unless otherwise specified.⁽¹⁾⁽²⁾⁽³⁾

Driver Supply Voltage and Operating Temperature Ranges, unless otherwise specified.							
Symbol	Parameter	Conditions	Pin	Min	Typ	Max	Units
LVCMOS Input DC Specifications (Driver Inputs, ENABLE Pins)							
V _{IH}	Input High Voltage		D _{IN} EN EN	2.0		V _{DD}	V
V _{IL}	Input Low Voltage			GND		0.8	V
I _{IH}	Input High Current	V _{IN} = V _{DD}		−10	1	+10	μA
I _{IL}	Input Low Current	V _{IN} = GND		−10	−0.1	+10	μA
V _{CL}	Input Clamp Voltage	I _{CL} = −18 mA		−1.5	−0.6		V
LVDS Output DC Specifications (Driver Outputs)							

- (1) Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except: V_{TH} , V_{TL} , V_{OD} and ΔV_{OD} .
- (2) All typical values are given for: $V_{DD} = +3.3$ V, $T_A = +25^\circ\text{C}$.
- (3) The DS90LV049's drivers are current mode devices and only function within datasheet specifications when a resistive load is applied to their outputs. The typical range of the resistor values is 90 Ω to 110 Ω .

ELECTRICAL CHARACTERISTICS (continued)

Over supply voltage and operating temperature ranges, unless otherwise specified.⁽¹⁾⁽²⁾⁽³⁾

Symbol	Parameter	Conditions	Pin	Min	Typ	Max	Units
V _{OD}	Differential Output Voltage	R _L = 100 Ω (Figure 1)	D _{OUT-} D _{OUT+}	250	350	450	mV
ΔV _{OD}	Change in Magnitude of V _{OD} for Complementary Output States				1	35	mV
V _{OS}	Offset Voltage			1.125	1.23	1.375	V
ΔV _{OS}	Change in Magnitude of V _{OS} for Complementary Output States				1	25	mV
I _{OS}	Output Short Circuit Current ⁽⁴⁾	ENABLED, D _{IN} = V _{DD} , D _{OUT+} = 0 V or D _{IN} = GND, D _{OUT-} = 0 V			-5.8	-9.0	mA
I _{OSD}	Differential Output Short Circuit Current ⁽⁴⁾	ENABLED, V _{OD} = 0 V			-5.8	-9.0	mA
I _{OFF}	Power-off Leakage	V _{OUT} = 0 V or 3.6 V V _{DD} = 0 V or Open		-20	±1	+20	μA
I _{OZ}	Output TRI-STATE Current	EN = 0 V and $\overline{\text{EN}}$ = V _{DD} V _{OUT} = 0 V or V _{DD}	-10	±1	+10	μA	
LVDS Input DC Specifications (Receiver Inputs)							
V _{TH}	Differential Input High Threshold	V _{CM} = 1.2 V, 0.05 V, 2.35 V	R _{IN+} R _{IN-}		-15	35	mV
V _{TL}	Differential Input Low Threshold			-100	-15		mV
V _{CMR}	Common-Mode Voltage Range	V _{ID} = 100 mV, V _{DD} =3.3 V		0.05		3	V
I _{IN}	Input Current	V _{DD} =3.6 V V _{IN} =0 V or 2.8 V		-12	±4	+12	μA
		V _{DD} =0 V V _{IN} =0 V or 2.8 V or 3.6 V		-10	±1	+10	μA
LVCMOS Output DC Specifications (Receiver Outputs)							
V _{OH}	Output High Voltage	I _{OH} = -0.4 mA, V _{ID} = 200 mV	R _{OUT}	2.7	3.3		V
V _{OL}	Output Low Voltage	I _{OL} = 2 mA, V _{ID} = 200 mV			0.05	0.25	V
I _{OZ}	Output TRI-STATE Current	Disabled, V _{OUT} =0 V or V _{DD}		-10	±1	+10	μA
General DC Specifications							
I _{DD}	Power Supply Current ⁽⁵⁾	EN = 3.3 V	V _{DD}		21	35	mA
I _{DDZ}	TRI-State Supply Current	EN = 0 V			15	25	mA

(4) Output short circuit current (I_{OS}) is specified as magnitude only, minus sign indicates direction only.

(5) Both driver and receiver inputs are static. All LVDS outputs have $100\ \Omega$ load. All LVC MOS outputs are floating. None of the outputs have any lumped capacitive load.

SWITCHING CHARACTERISTICS

 $V_{DD} = +3.3V \pm 10\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ ^{(1) (2)}

Symbol	Parameter	Conditions	Min	Typ	Max	Units
LVDS Outputs (Driver Outputs)						
t _{PHLD}	Differential Propagation Delay High to Low	R _L = 100 Ω (Figure 2 and Figure 3)		0.7	2	ns
t _{PLHD}	Differential Propagation Delay Low to High			0.7	2	ns
t _{SKD1}	Differential Pulse Skew t _{PHLD} – t _{PLHD} ⁽³⁾⁽⁴⁾		0	0.05	0.4	ns
t _{SKD2}	Differential Channel-to-Channel Skew ⁽³⁾⁽⁵⁾		0	0.05	0.5	ns
t _{SKD3}	Differential Part-to-Part Skew ⁽³⁾⁽⁶⁾		0		1.0	ns
t _{TLH}	Rise Time ⁽³⁾		0.2	0.4	1	ns
t _{THL}	Fall Time ⁽³⁾		0.2	0.4	1	ns
t _{PHZ}	Disable Time High to Z	R _L = 100 Ω (Figure 4 and Figure 5)		1.5	3	ns
t _{PLZ}	Disable Time Low to Z			1.5	3	ns
t _{PZH}	Enable Time Z to High		1	3	6	ns
t _{PZL}	Enable Time Z to Low		1	3	6	ns
f _{MAX}	Maximum Operating Frequency ⁽⁷⁾		200	250		MHz
LVCMOS Outputs (Receiver Outputs)						
t _{PHL}	Propagation Delay High to Low	(Figure 6 and Figure 7)	0.5	2	3.5	ns
t _{PLH}	Propagation Delay Low to High		0.5	2	3.5	ns
t _{SK1}	Pulse Skew t _{PHL} – t _{PLH} ⁽⁸⁾		0	0.05	0.4	ns
t _{SK2}	Channel-to-Channel Skew ⁽⁹⁾		0	0.05	0.5	ns
t _{SK3}	Part-to-Part Skew ⁽¹⁰⁾		0		1.0	ns
t _{TLH}	Rise Time ⁽³⁾		0.3	0.9	1.4	ns
t _{THL}	Fall Time ⁽³⁾	(Figure 8 and Figure 9)	0.3	0.75	1.4	ns
t _{PHZ}	Disable Time High to Z		3	5.6	8	ns
t _{PLZ}	Disable Time Low to Z		3	5.4	8	ns
t _{PZH}	Enable Time Z to High		2.5	4.6	7	ns
t _{PZL}	Enable Time Z to Low		2.5	4.6	7	ns
f _{MAX}	Maximum Operating Frequency ⁽¹¹⁾			200	250	

(1) All typical values are given for: $V_{DD} = +3.3\text{ V}$, $T_A = +25^\circ\text{C}$.

(2) Generator waveform for all tests unless otherwise specified: $f = 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 1\text{ ns}$, and $t_f \leq 1\text{ ns}$.

(3) These parameters are specified by design. The limits are based on statistical analysis of the device performance over PVT (process, voltage, temperature) ranges.

(4) t_{SKD1} or differential pulse skew is defined as $|t_{PHLD} - t_{PLHD}|$. It is the magnitude difference in the differential propagation delays between the positive going edge and the negative going edge of the same driver channel.

(5) t_{SKD2} or differential channel-to-channel skew is defined as the magnitude difference in the differential propagation delays between two driver channels on the same device.

(6) t_{SKD3} or differential part-to-part skew is defined as $|t_{PLHD\text{ Max}} - t_{PLHD\text{ Min}}|$ or $|t_{PHLD\text{ Max}} - t_{PHLD\text{ Min}}|$. It is the difference between the minimum and maximum specified differential propagation delays. This specification applies to devices at the same V_{DD} and within 5°C of each other within the operating temperature range.

(7) f_{MAX} generator input conditions: $t_r = t_f < 1\text{ ns}$ (0% to 100%), 50% duty cycle, 0 V to 3 V. Output Criteria: duty cycle = 45%/55%, $V_{OD} > 250\text{ mV}$, all channels switching.

(8) t_{SK1} or pulse skew is defined as $|t_{PHL} - t_{PLH}|$. It is the magnitude difference in the propagation delays between the positive going edge and the negative going edge of the same receiver channel.

(9) t_{SK2} or channel-to-channel skew is defined as the magnitude difference in the propagation delays between two receiver channels on the same device.

(10) t_{SK3} or part-to-part skew is defined as $|t_{PLH\text{ Max}} - t_{PLH\text{ Min}}|$ or $|t_{PHL\text{ Max}} - t_{PHL\text{ Min}}|$. It is the difference between the minimum and maximum specified propagation delays. This specification applies to devices at the same V_{DD} and within 5°C of each other within the operating temperature range.

(11) f_{MAX} generator input conditions: $t_r = t_f < 1\text{ ns}$ (0% to 100%), 50% duty cycle, $V_{ID} = 200\text{ mV}$, $V_{CM} = 1.2\text{ V}$. Output Criteria: duty cycle = 45%/55%, $V_{OH} > 2.7\text{ V}$, $V_{OL} < 0.25\text{ V}$, all channels switching.

PARAMETER MEASUREMENT INFORMATION

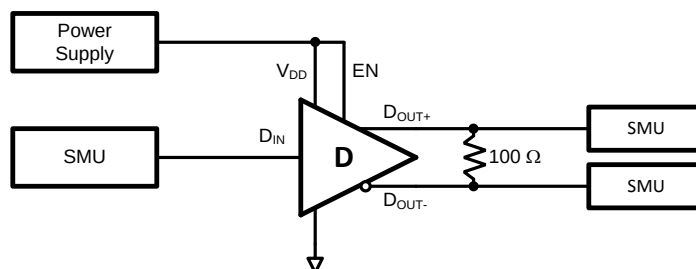


Figure 1. Driver V_{OD} and V_{OS} Test Circuit

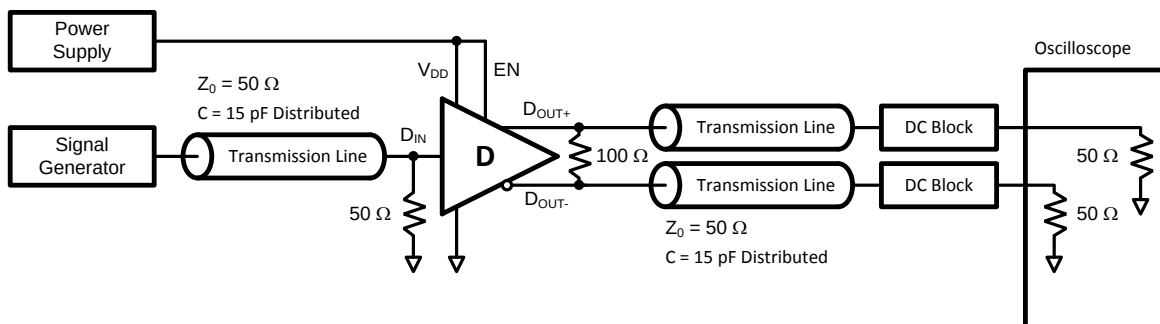


Figure 2. Driver Propagation Delay and Transition Time Test Circuit

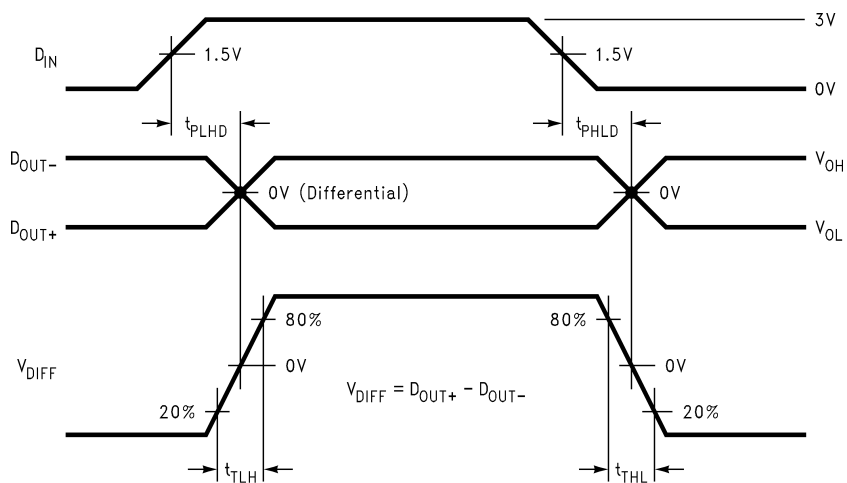


Figure 3. Driver Propagation Delay and Transition Time Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)

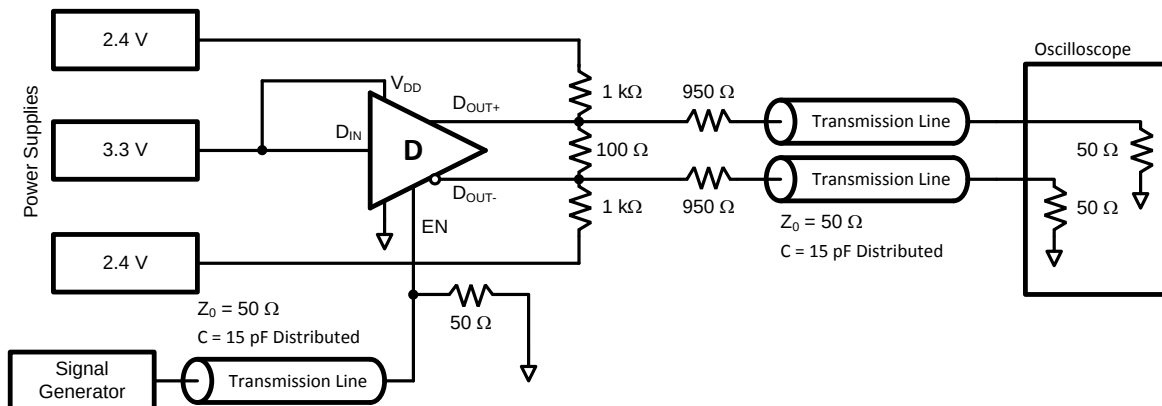


Figure 4. Driver TRI-STATE Delay Test Circuit

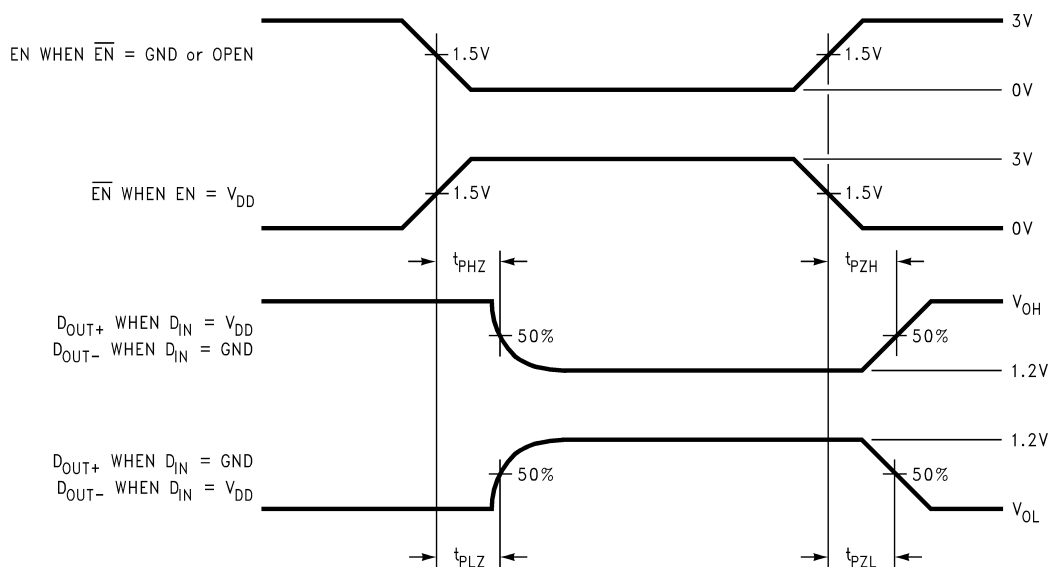


Figure 5. Driver TRI-STATE Delay Waveform

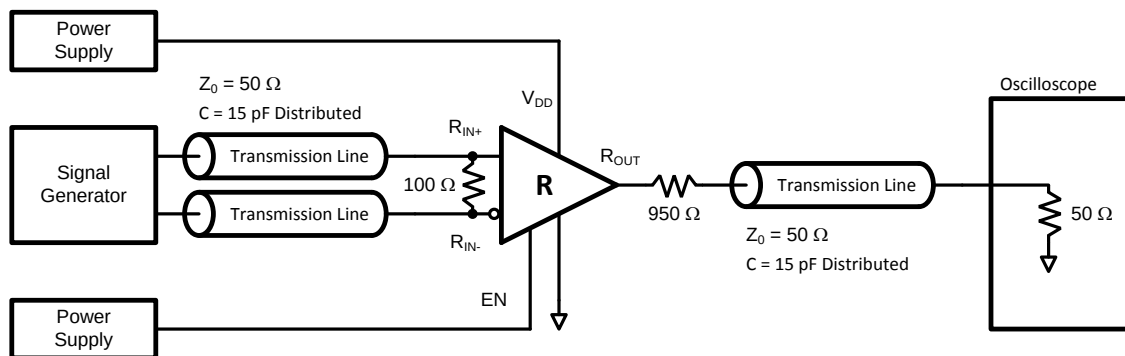
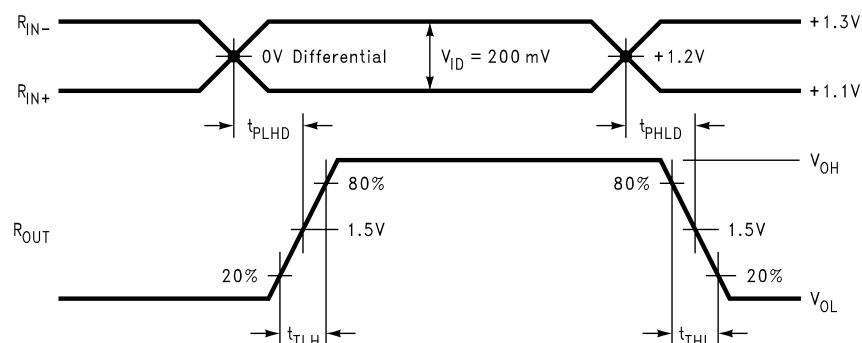
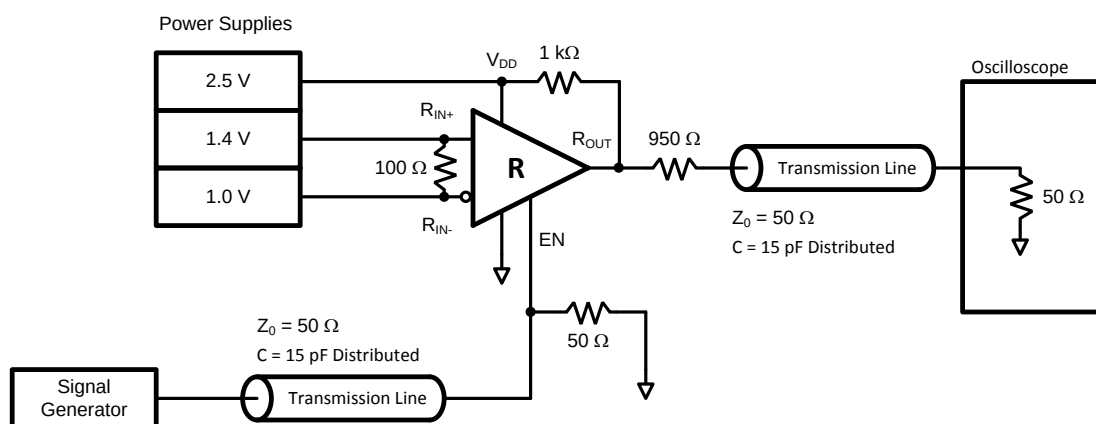


Figure 6. Receiver Propagation Delay and Transition Time Test Circuit

PARAMETER MEASUREMENT INFORMATION (continued)**Figure 7. Receiver Propagation Delay and Transition Time Waveforms****Figure 8. Receiver TRI-STATE Delay Test Circuit**

PARAMETER MEASUREMENT INFORMATION (continued)

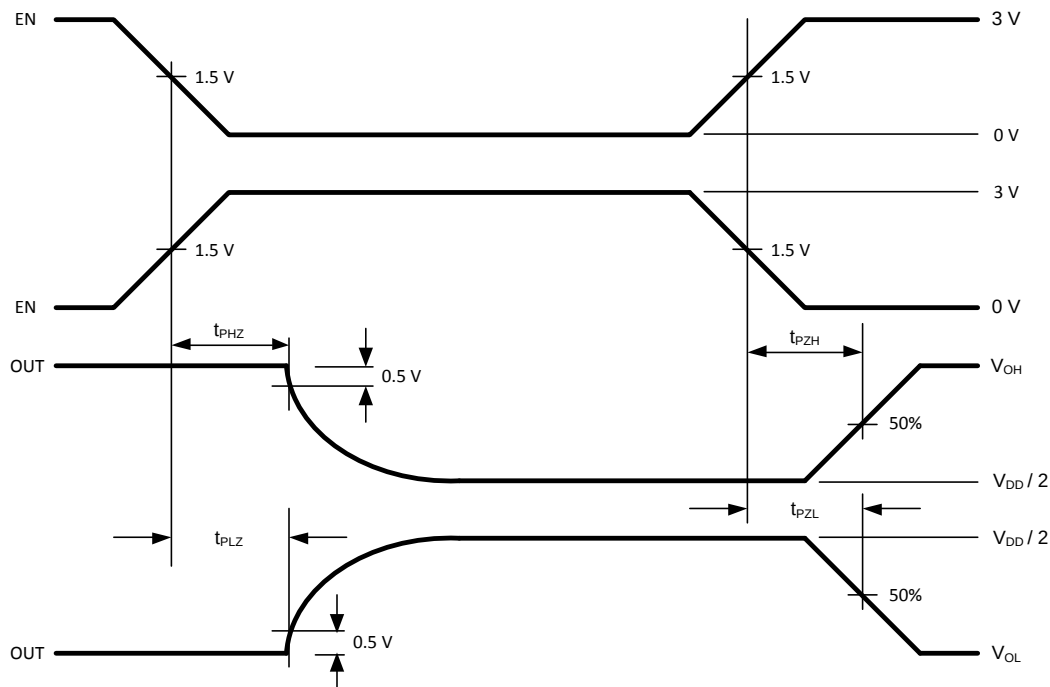


Figure 9. Receiver TRI-STATE Delay Waveforms

TYPICAL APPLICATION

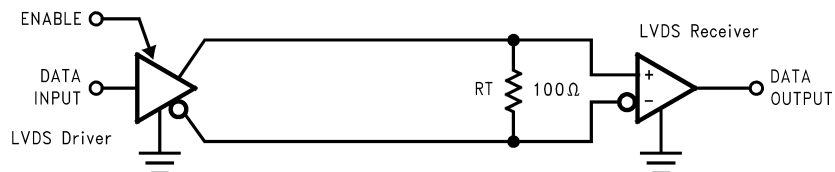


Figure 10. Point-to-Point Application

APPLICATION INFORMATION

General application guidelines and hints for LVDS drivers and receivers may be found in the following application notes: LVDS Owner's Manual (lit #550062-002), AN-808 ([SNLA028](#)), AN-977 ([SNLA166](#)), AN-971 ([SNLA165](#)), AN-916 ([SNLA219](#)), AN-805 ([SNOA233](#)), AN-903 ([SNLA034](#)).

LVDS drivers and receivers are intended to be primarily used in an uncomplicated point-to-point configuration as is shown in [Figure 10](#). This configuration provides a clean signaling environment for the fast edge rates of the drivers. The receiver is connected to the driver through a balanced media which may be a standard twisted pair cable, a parallel pair cable, or simply PCB traces. Typically, the characteristic differential impedance of the media is in the range of 100 Ω . A termination resistor of 100 Ω (selected to match the media), and is located as close to the receiver input pins as possible. The termination resistor converts the driver output current (current mode) into a voltage that is detected by the receiver. Other configurations are possible such as a multi-receiver configuration, but the effects of a mid-stream connector(s), cable stub(s), and other impedance discontinuities as well as ground shifting, noise margin limits, and total termination loading must be taken into account.

The TRI-STATE function allows the device outputs to be disabled, thus obtaining an even lower power state when the transmission of data is not required.

The DS90LV049 has a flow-through pinout that allows for easy PCB layout. The LVDS signals on one side of the device easily allows for matching electrical lengths of the differential pair trace lines between the driver and the receiver as well as allowing the trace lines to be close together to couple noise as common-mode. Noise isolation is achieved with the LVDS signals on one side of the device and the TTL signals on the other side.

POWER DECOUPLING RECOMMENDATIONS

Bypass capacitors must be used on power pins. Use high frequency ceramic (surface mount is recommended) 0.1 μF and 0.001 μF capacitors in parallel at the power supply pin with the smallest value capacitor closest to the device supply pin. Additional scattered capacitors over the printed circuit board will improve decoupling. Multiple vias should be used to connect the decoupling capacitors to the power planes. A 10 μF (35 V) or greater solid tantalum capacitor should be connected at the power entry point on the printed circuit board between the supply and ground.

PC BOARD CONSIDERATIONS

Use at least 4 PCB layers (top to bottom); LVDS signals, ground, power, TTL signals.

Isolate TTL signals from LVDS signals, otherwise the TTL may couple onto the LVDS lines. It is best to put TTL and LVDS signals on different layers which are isolated by a power/ground plane(s).

Keep drivers and receivers as close to the (LVDS port side) connectors as possible.

DIFFERENTIAL TRACES

Use controlled impedance traces which match the differential impedance of your transmission medium (i.e. cable) and termination resistor. Run the differential pair trace lines as close together as possible as soon as they leave the IC (stubs should be < 10 mm long). This will help eliminate reflections and ensure noise is coupled as common-mode. In fact, we have seen that differential signals which are 1 mm apart radiate far less noise than traces 3 mm apart since magnetic field cancellation is much better with the closer traces. In addition, noise induced on the differential lines is much more likely to appear as common-mode which is rejected by the receiver.

Match electrical lengths between traces to reduce skew. Skew between the signals of a pair means a phase difference between signals which destroys the magnetic field cancellation benefits of differential signals and EMI will result. (Note the velocity of propagation, $v = c/\epsilon_r$ where c (the speed of light) = 0.2997 mm/ps or 0.0118 in/ps). Do not rely solely on the autoroute function for differential traces. Carefully review dimensions to match differential impedance and provide isolation for the differential lines. Minimize the number of vias and other discontinuities on the line.

Avoid 90° turns (these cause impedance discontinuities). Use arcs or 45° bevels.

Within a pair of traces, the distance between the two traces should be minimized to maintain common-mode rejection of the receivers. On the printed circuit board, this distance should remain constant to avoid discontinuities in differential impedance. Minor violations at connection points are allowable.

TERMINATION

Use a termination resistor which best matches the differential impedance of your transmission line. The resistor should be between 90 Ω and 130 Ω . Remember that the current mode outputs need the termination resistor to generate the differential voltage. LVDS will not work without resistor termination. Typically, connecting a single resistor across the pair at the receiver end will suffice.

Surface mount 1% to 2% resistors are best. PCB stubs, component lead, and the distance from the termination to the receiver inputs should be minimized. The distance between the termination resistor and the receiver should be < 10 mm (12 mm MAX).

PROBING LVDS TRANSMISSION LINES

Always use high impedance (> 100 k Ω), low capacitance (< 2 pF) scope probes with a wide bandwidth (1 GHz) scope. Improper probing will give deceiving results.

CABLES AND CONNECTORS, GENERAL COMMENTS

When choosing cable and connectors for LVDS it is important to remember:

Use controlled impedance media. The cables and connectors you use should have a matched differential impedance of about 100 Ω . They should not introduce major impedance discontinuities.

Balanced cables (e.g. twisted pair) are usually better than unbalanced cables (ribbon cable, simple coax.) for noise reduction and signal quality. Balanced cables tend to generate less EMI due to field canceling effects and also tend to pick up electromagnetic radiation a common-mode (not differential mode) noise which is rejected by the receiver.

FAIL-SAFE FEATURE

An LVDS receiver is a high gain, high speed device that amplifies a small differential signal (20 mV) to CMOS logic levels. Due to the high gain and tight threshold of the receiver, care should be taken to prevent noise from appearing as a valid signal.

The receiver's internal fail-safe circuitry is designed to source/sink a small amount of current, providing fail-safe protection (a stable known state of HIGH output voltage) for floating receiver inputs.

The DS90LV049 has two receivers, and if an application requires a single receiver, the unused receiver inputs should be left OPEN. Do not tie unused receiver inputs to ground or any other voltages. The input is biased by internal high value pull up and pull down current sources to set the output to a HIGH state. This internal circuitry will ensure a HIGH, stable output state for open inputs.

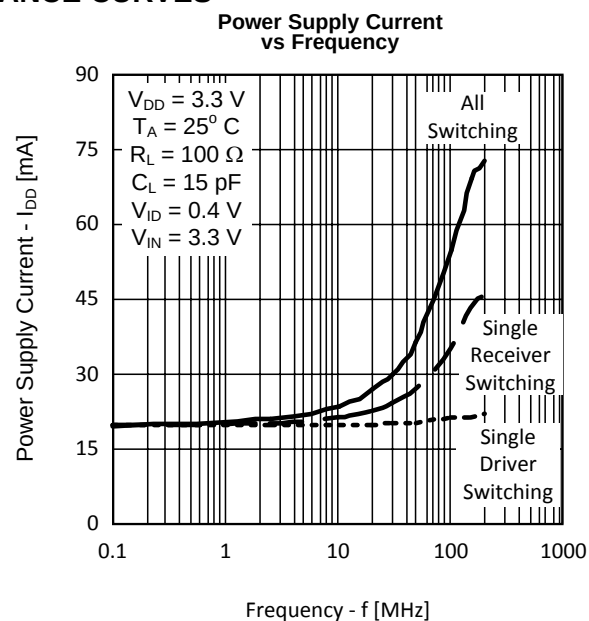
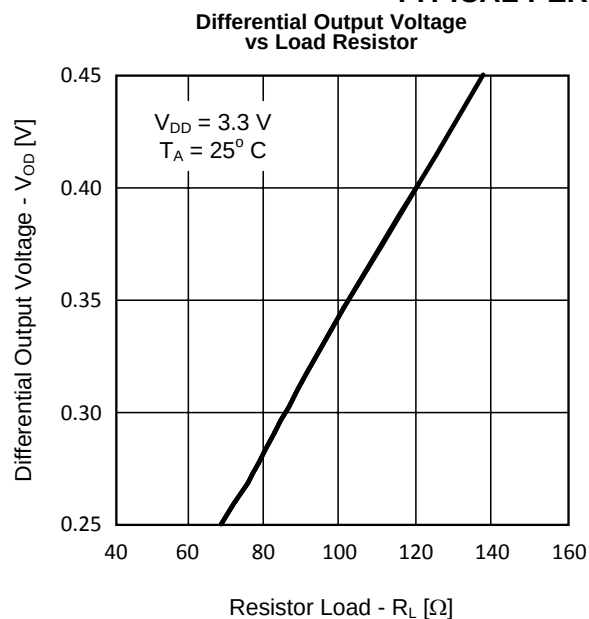
External lower value pull up and pull down resistors (for a stronger bias) may be used to boost fail-safe in the presence of higher noise levels. The pull up and pull down resistors should be in the 5 k Ω to 15 k Ω range to minimize loading and waveform distortion to the driver. The common-mode bias point should be set to approximately 1.2 V (less than 1.75 V) to be compatible with the internal circuitry.

For more information on failsafe biasing of LVDS interfaces please refer to AN-1194 ([SNLA051](#)).

PIN DESCRIPTIONS

Pin No.	Name	Description
10, 11	D _{IN}	Driver input pins, LVCMOS levels. There is a pull-down current source present.
6, 7	D _{OUT+}	Non-inverting driver output pins, LVDS levels.
5, 8	D _{OUT-}	Inverting driver output pins, LVDS levels.
2, 3	R _{IN+}	Non-inverting receiver input pins, LVDS levels. There is a pull-up current source present.
1, 4	R _{IN-}	Inverting receiver input pins, LVDS levels. There is a pull-down current source present.
14, 15	R _{OUT}	Receiver output pins, LVCMOS levels.
9, 16	EN, $\overline{\text{EN}}$	Enable and Disable pins. There are pull-down current sources present at both pins.
12	V _{DD}	Power supply pin.
13	GND	Ground pin.

TYPICAL PERFORMANCE CURVES



REVISION HISTORY

Changes from Revision C (April 2013) to Revision D	Page
• Changed layout of National Data Sheet to TI format	11

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS90LV049TMT/NOPB	Active	Production	TSSOP (PW) 16	92 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	90LV049 TMT
DS90LV049TMT/NOPB.A	Active	Production	TSSOP (PW) 16	92 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	90LV049 TMT
DS90LV049TMT/NOPB.B	Active	Production	TSSOP (PW) 16	92 TUBE	-	Call TI	Call TI	-40 to 85	
DS90LV049TMTX/NOPB	Active	Production	TSSOP (PW) 16	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	90LV049 TMT
DS90LV049TMTX/NOPB.A	Active	Production	TSSOP (PW) 16	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	90LV049 TMT
DS90LV049TMTX/NOPB.B	Active	Production	TSSOP (PW) 16	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

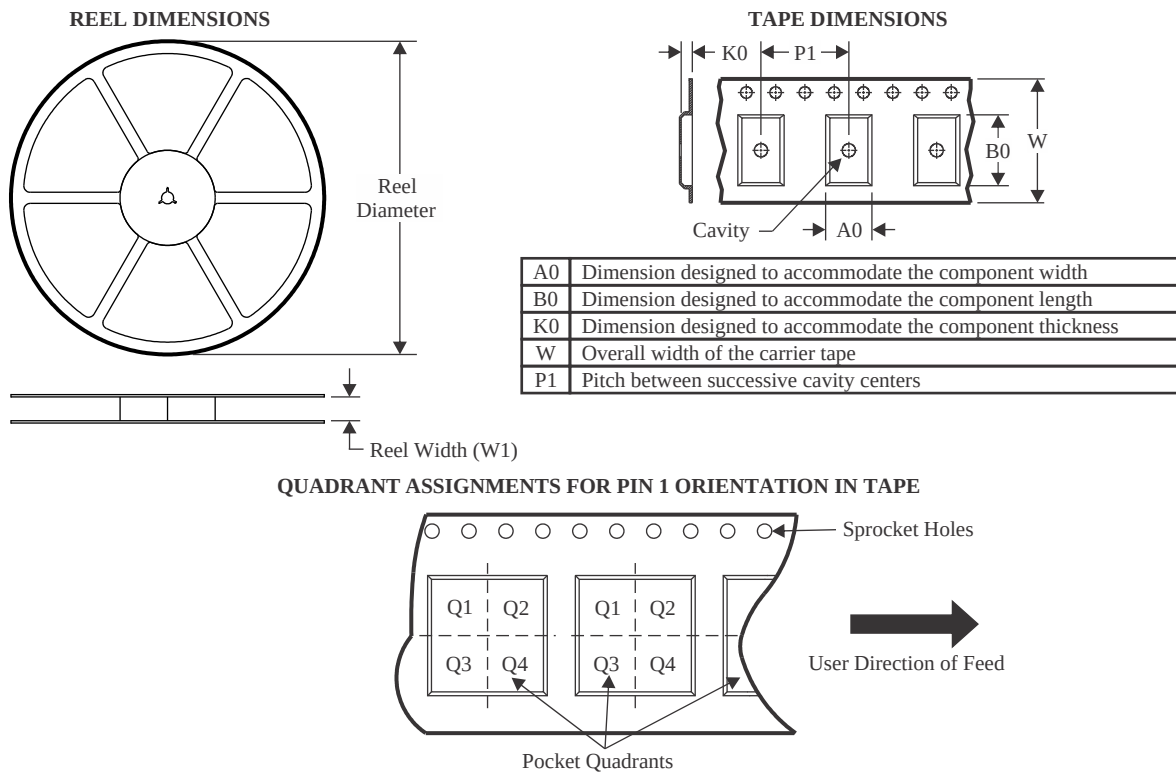
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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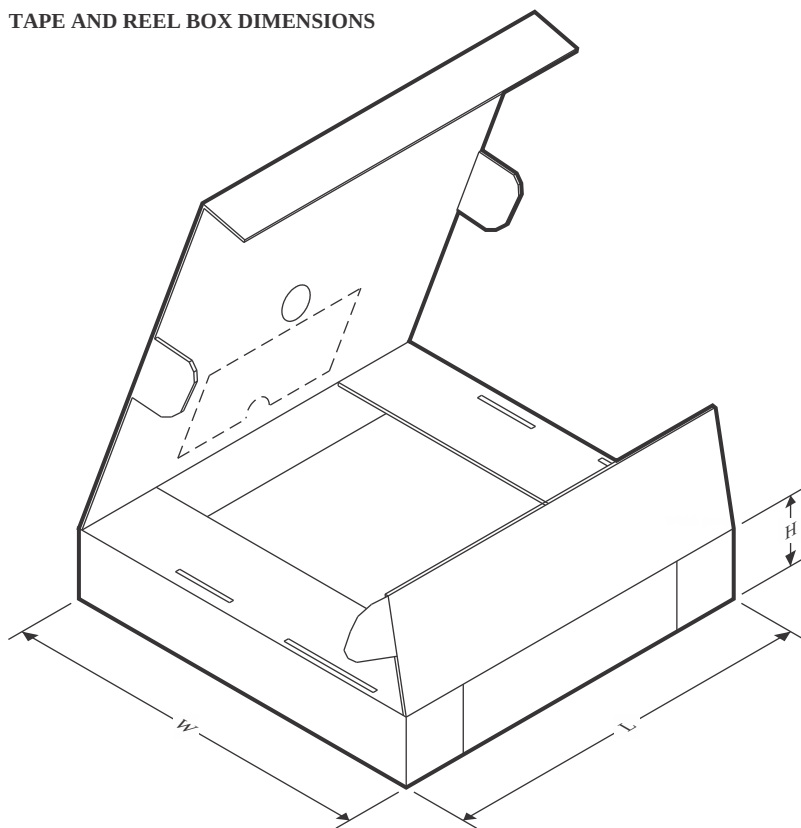
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS90LV049TMTX/NOPB	TSSOP	PW	16	2500	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

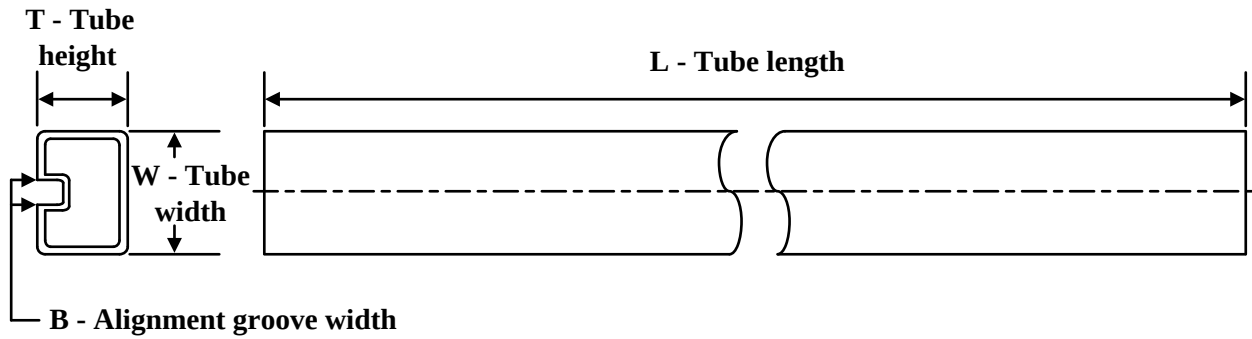
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

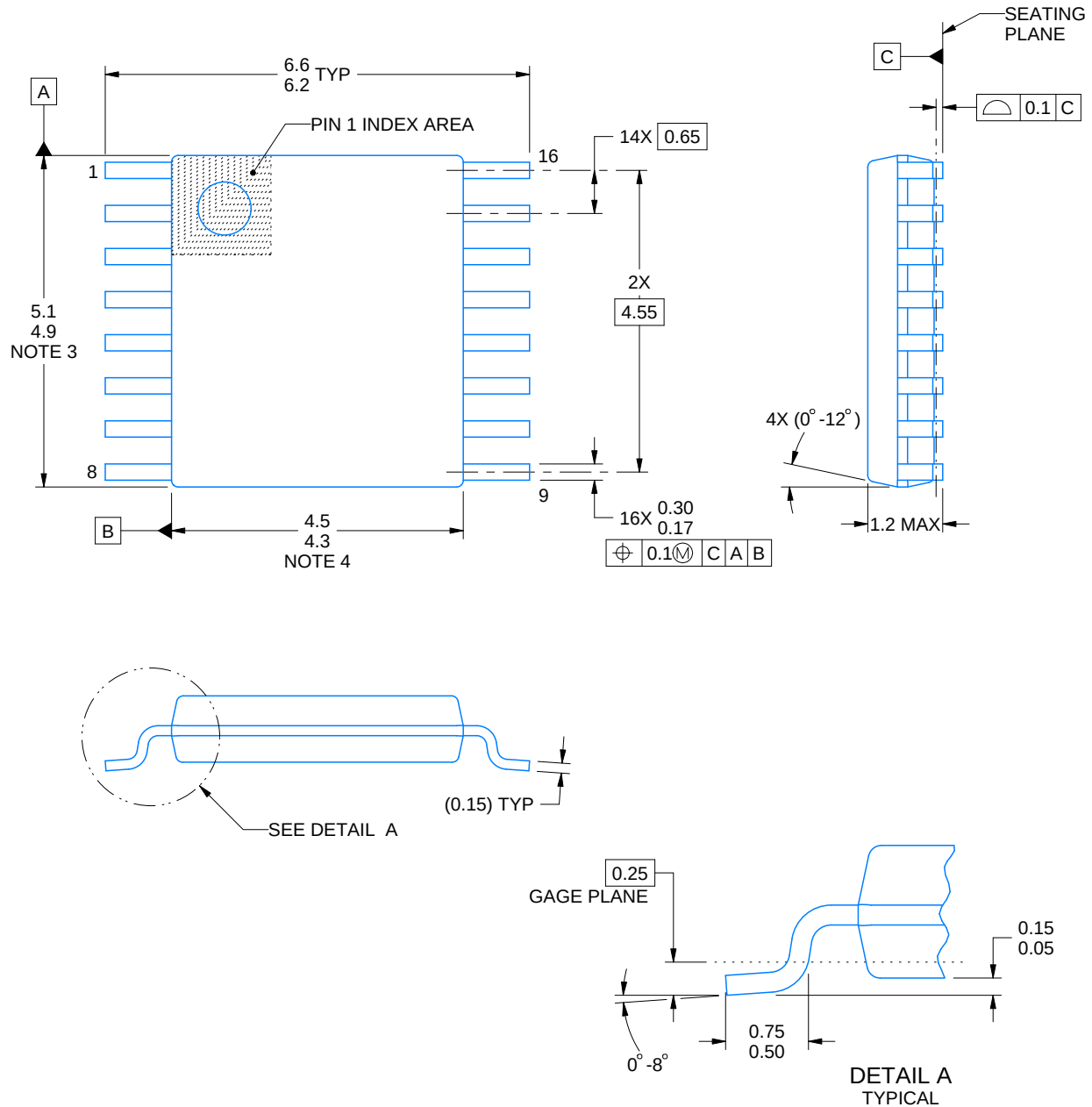
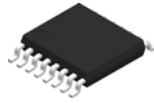
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS90LV049TMTX/NOPB	TSSOP	PW	16	2500	367.0	367.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS90LV049TMT/NOPB	PW	TSSOP	16	92	495	8	2514.6	4.06
DS90LV049TMT/NOPB.A	PW	TSSOP	16	92	495	8	2514.6	4.06



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NOTES:

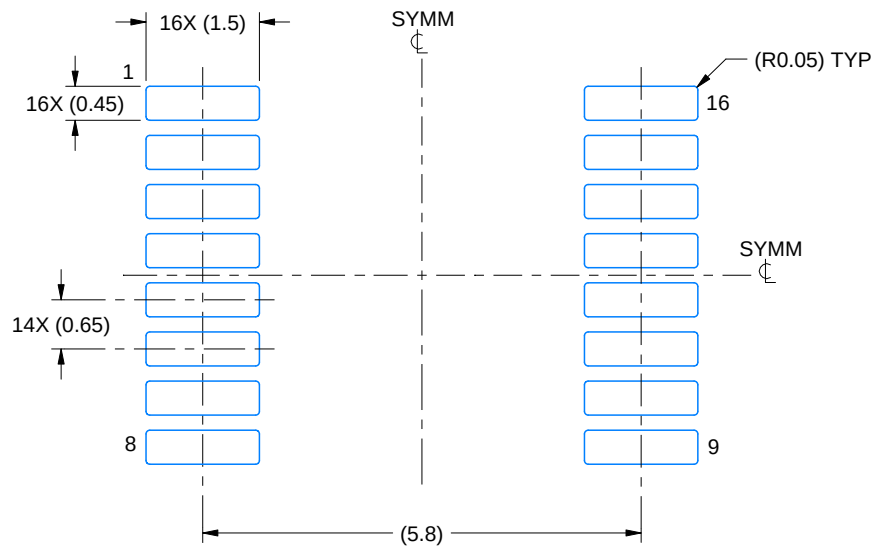
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

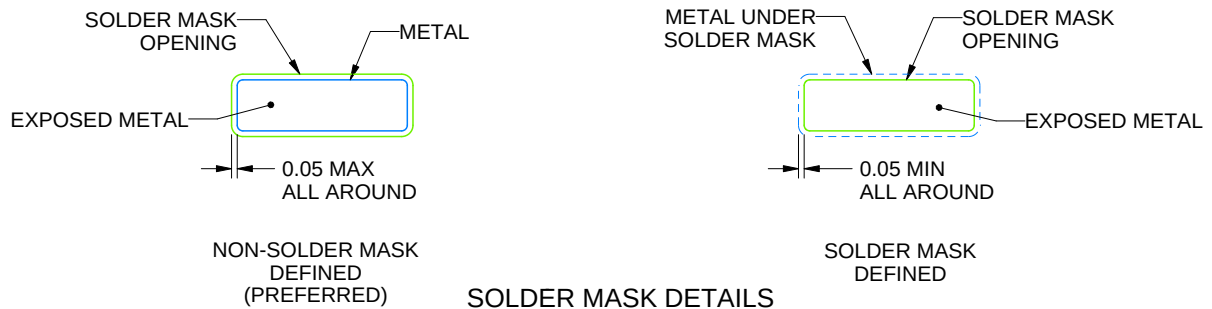
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

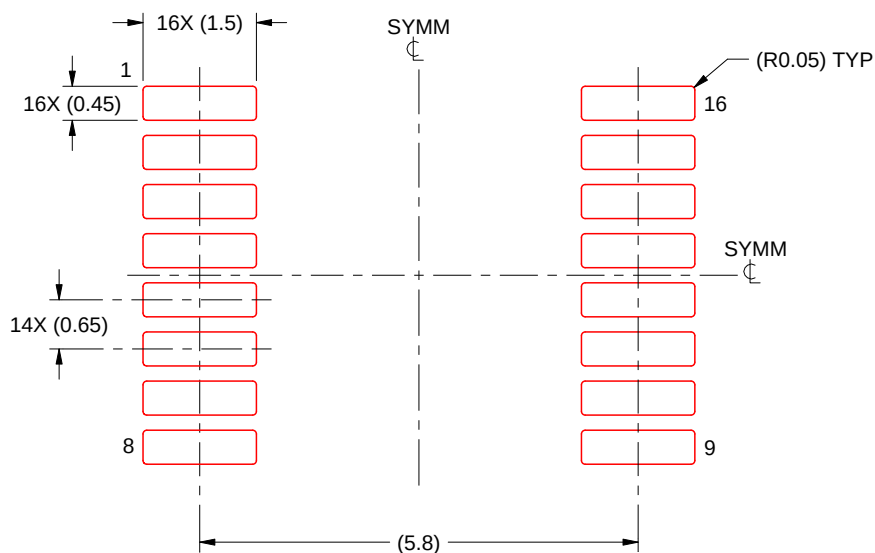
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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